




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8L152R6T6	J45W*768XXXZ	A	959	2016-12-08
Amount		UoM	Unit type	ST ECOPACK Grade
350.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L bend	
Comment	LQFP 64 10x10x1.4			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	J45W*768XXZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	5.932	mg	supplier	die	Silicon (Si)	7440-21-3		5.726	mg	965273	16360
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	2697	46
Die or Dies				supplier	metallization	Copper (Cu)	7440-50-8		0.053	mg	8935	151
Die or Dies				supplier	metallization	Tantalum (Ta)	7440-25-7		0.030	mg	5057	86
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1349	23
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.014	mg	2360	40
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.085	mg	14329	243
Lead-frame	Other inorganic materials	66.420	mg	supplier	alloy	Copper (Cu)	7440-50-8		63.896	mg	962001	182560
Lead-frame				supplier	alloy	Nickel (Ni)	7440-02-0		1.993	mg	30000	5693
Lead-frame				supplier	alloy	Silicium (Si)	7440-21-3		0.432	mg	6500	1233
Lead-frame				supplier	alloy	Magnesium (Mg)	7439-95-4		0.100	mg	1500	285
Die Attach	Other inorganic materials	3.703	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.984	mg	806000	8527
Die Attach				supplier	glue or soft solder	acrylate	65983-31-5		0.222	mg	60000	635
Die Attach				supplier	glue or soft solder	Epoxy Cresol Novolak	29690-82-2		0.111	mg	30000	317
Die Attach				supplier	glue or soft solder	Butadiene copolymer	68891-50-9		0.037	mg	10000	106
Die Attach				supplier	glue or soft solder	poly butadiene derivative	Proprietary		0.222	mg	60000	635
Die Attach				supplier	glue or soft solder	[3-(2,3-epoxypropoxy)propyl] trimethoxysilane	2530-83-8		0.074	mg	20000	212
Die Attach				supplier	glue or soft solder	peroxyde de cyclohexylidènebis (tert-butyle)	3006-86-8		0.037	mg	10000	106
Die Attach				supplier	glue or soft solder	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.015	mg	4000	42
Wires	Other inorganic materials	1.076	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		1.065	mg	990000	3042
Wires				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.011	mg	10000	31
Encapsulation	Other inorganic materials	266.674	mg	supplier	Moulding Compound	Epoxy Resin	Proprietary		17.025	mg	63842	48643
Encapsulation				supplier	Moulding Compound	Phenol Resin	Proprietary		11.350	mg	42561	32429
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		235.802	mg	884233	673720
Encapsulation				supplier	Moulding Compound	Quartz	14808-60-7		0.681	mg	2554	1946
Encapsulation				supplier	Moulding Compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.135	mg	4256	3243
Encapsulation				supplier	Moulding Compound	Carbon black	1333-86-4		0.681	mg	2554	1946
Finishing	Other inorganic materials	6.196	mg	supplier	connections coating	Tin (Sn)	7440-31-5		6.196	mg	1000000	17703